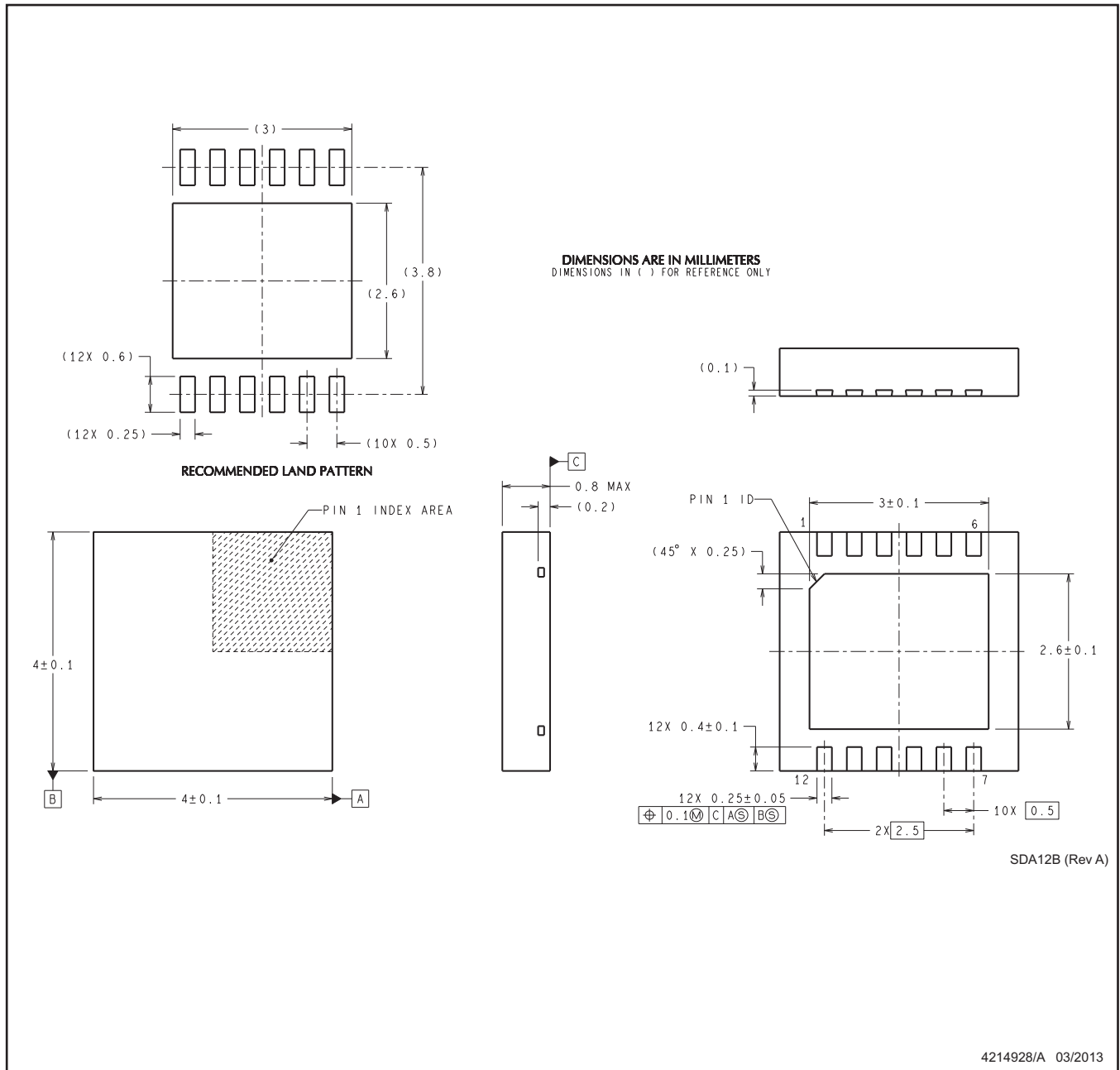


MECHANICAL DATA

DNT0012B

WSO - 0.8mm max height

SON (PLASTIC SMALL OUTLINE - NO LEAD)



- NOTES: 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is designed to be soldered to a thermal pad on the board for thermal and mechanical performance. For more information, refer to QFN/SON PCB application note in literature No. SLUA271 (www.ti.com/lit/slua271).

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